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Atty. Dkt. No. 039153-0457 (G1162)

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Lopatin et al.

Title: METHOD OF USING TERNARY
COPPER ALLOY TO OBTAIN A
LOW RESISTANCE AND LARGE
GRAIN SIZE INTERCONNECT

Appl. No.: 09/994,395

Filing Date: 11/26/2001

Examiner: Unknown

Art Unit: Unknown

CERTIFICATE OF MAILING I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on the date below. <u>SANDRA A. MURPHY</u> (Printed Name) <u>Sandra A. Murphy</u> (Signature) <u>October 22, 2002</u> (Date of Deposit)
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REQUEST TO RESCIND PREVIOUS NONPUBLICATION REQUEST

35 U.S.C. 122(b)(2)(B)(iii)

Commissioner for Patents
Washington, D.C. 20231

Sir:

Applicants hereby rescind the previous request that the above-identified application not be published under 35 U.S.C. 122(b).

Respectfully submitted,

Date Oct. 22, 2002

By

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